

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	2312	257/723,724.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT
2	BRS	L2	1113	438/107,109,110,117.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT
3	BRS	L3	3364	1 2	USPAT; US-PGPUB; EPO; JPO; DERWENT
4	BRS	L4	1095	3 and (ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT
5	BRS	L5	905	4 and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT
6	BRS	L6	803	5 and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT
7	BRS	L7	596	6 and (resin sealing encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT
8	BRS	L8	218	7 and (second near1 (chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT
9	BRS	L9	64	8 and (bga (ball adj grid adj array))	USPAT; US-PGPUB; EPO; JPO; DERWENT
10	BRS	L10	2	("5721452"   "6133637").PN.	USPAT
11	BRS	L12	34	("4954878"   "5099306"   "5109320"   "5128831"   "5222014"   "5252857"   "5291061"   "5300801"   "5323060"   "5403784"   "5422435"   "5434745"   "5466627"   "5473814"   "5477082"   "5481134"   "5494841"   "5495398"   "5496775"   "5498902"   "5498905"   "5506756"   "5508565"   "5512765"   "5512780"   "5513076"   "5535101"   "5594275"   "5639696"   "5705858"   "5715144"   "5728606"   "5729440"   "6051878").PN.	USPAT
12	BRS	L14	12	("4862322"   "5291061"   "5323060"   "5422435"   "5735030"   "5773896"   "6005778"   "6051886"   "6097097"   "6222265"   "6232148"   "6252305").PN.	USPAT
13	BRS	L16	6	("3855693"   "5148265"   "5408127"   "5814883"   "5858815"   "5950070").PN.	USPAT
14	BRS	L18	4959	(bga (ball adj grid adj array)) near2 (package packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
1	2002/05/17 06:42			0
2	2002/05/17 06:43			0
3	2002/05/17 06:43			0
4	2002/05/17 06:43			0
5	2002/05/17 06:43			0
6	2002/05/17 07:44			0
7	2002/05/17 07:45			0
8	2002/05/17 07:44			0
9	2002/05/17 07:35			0
10	2002/05/17 06:55			0
11	2002/05/17 07:21			0
12	2002/05/17 07:25			0
13	2002/05/17 07:28			0
14	2002/05/17 08:09			0

	Type	L #	Hits	Search Text	DBs
15	BRS	L21	276	18 and (multi adj chip adj module)	USPAT; US-PGPUB; EPO; JPO; DERWENT
16	BRS	L22	269	21 not 9	USPAT; US-PGPUB; EPO; JPO; DERWENT
17	BRS	L23	229	22 and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT
18	BRS	L24	25	23 and (second near1 (chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT
19	BRS	L25	223	23 and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT
20	BRS	L26	168	25 and (resin sealing encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT
21	BRS	L27	17	("4949224"   "4996585"   "5148265"   "5200810"   "5289059"   "5347159"   "5362656"   "5365119"   "5382829"   "5387874"   "5390223"   "5416435"   "5497116"   "5528083"   "5581776"   "5663106"   "5753974").PN.	USPAT
22	BRS	L28	5	5872700.URPN.	USPAT
23	BRS	L29	215	18 and mcm	USPAT; US-PGPUB; EPO; JPO; DERWENT
24	BRS	L30	122	29 not 26	USPAT; US-PGPUB; EPO; JPO; DERWENT
25	BRS	L32	4	("4761681"   "5151769"   "5394303"   "5644167").PN.	USPAT
26	BRS	L33	12	("5509553"   "5525834"   "5530287"   "5578869"   "5660697"   "5660738"   "5723906"   "5724232"   "5830563"   "5837427"   "5866942"   "6080936").PN.	USPAT
27	BRS	L34	414	18 and ((multichip adj module) (multi adj chip adj module) mcm)	USPAT; US-PGPUB; EPO; JPO; DERWENT
28	BRS	L35	10513	(bga (ball adj grid adj array))	USPAT; US-PGPUB; EPO; JPO; DERWENT
29	BRS	L36	199	34 not 29	USPAT; US-PGPUB; EPO; JPO; DERWENT
30	BRS	L38	124	37 not 30	USPAT; US-PGPUB; EPO; JPO; DERWENT
31	BRS	L37	124	36 not 26	USPAT; US-PGPUB; EPO; JPO; DERWENT
32	BRS	L39	3	CHEN-JIAN-WEN	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
15	2002/05/17 07:40			0
16	2002/05/17 07:43			0
17	2002/05/17 07:43			0
18	2002/05/17 07:44			0
19	2002/05/17 07:45			0
20	2002/05/17 07:58			0
21	2002/05/17 07:54			0
22	2002/05/17 07:55			0
23	2002/05/17 08:08			0
24	2002/05/17 07:58			0
25	2002/05/17 08:01			0
26	2002/05/17 08:02			0
27	2002/05/17 08:48			0
28	2002/05/17 08:10			0
29	2002/05/17 08:10			0
30	2002/05/17 08:11			0
31	2002/05/17 08:11			0
32	2002/05/17 08:27			0

	Type	L #	Hits	Search Text	DBs
33	BRS	L40	938	35 and ((multichip adj module) (multi adj chip adj module) mcm)	USPAT; US-PGPUB; EPO; JPO; DERWENT
34	BRS	L41	306	35 with ((multichip adj module) (multi adj chip adj module) mcm)	USPAT; US-PGPUB; EPO; JPO; DERWENT
35	BRS	L42	238	41 not 36	USPAT; US-PGPUB; EPO; JPO; DERWENT
36	BRS	L43	168	42 not 29	USPAT; US-PGPUB; EPO; JPO; DERWENT
37	BRS	L44	168	43 not 30	USPAT; US-PGPUB; EPO; JPO; DERWENT
38	BRS	L45	168	44 not 9	USPAT; US-PGPUB; EPO; JPO; DERWENT
39	BRS	L46	93	45 and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT
40	BRS	L47	8	("5729437"   "5776798"   "5973263"   "5989982"   "5990545"   "6087202"   "6093584"   "6228676").PN.	USPAT
41	BRS	L48	6	("4992850"   "5504373"   "5817535"   "5953216"   "6008538"   "6087676").PN.	USPAT
42	BRS	L49	5	("4549200"   "5027190"   "5239198"   "5422514"   "5608261").PN.	USPAT
43	BRS	L50	3	5784264.URPN.	USPAT
44	BRS	L51	2	("4882657"   "5438224").PN.	USPAT
45	BRS	L52	19	4882657.URPN.	USPAT
46	BRS	L53	632	40 not 41	USPAT; US-PGPUB; EPO; JPO; DERWENT
47	BRS	L54	526	53 and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT
48	BRS	L55	280	54 not 29 not 30 not 36	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
33	2002/05/17 08:54			0
34	2002/05/17 09:03			0
35	2002/05/17 09:03			0
36	2002/05/17 09:03			0
37	2002/05/17 09:03			0
38	2002/05/17 09:04			0
39	2002/05/17 10:06			0
40	2002/05/17 09:06			0
41	2002/05/17 09:31			0
42	2002/05/17 10:00			0
43	2002/05/17 10:01			0
44	2002/05/17 10:02			0
45	2002/05/17 10:02			0
46	2002/05/17 10:05			0
47	2002/05/17 10:06			0
48	2002/05/17 10:18			0

	Type	L #	Hits	Search Text	DBs
49	BRS	L56	28	( "5311060"   "5329160"   "5365107"   "5468910"   "5552635"   "5585669"   "5598321"   "5629561"   "5650918"   "5656864"   "5703398"   "5710459"   "5724230"   "5789810"   "5852320"   "5881944"   "5882945"   "5886876"   "5889323"   "5898219"   "5907189"   "5909056"   "5931222"   "5939784"   "5956576"   "5977626"   "5982038"   "5990418" ) .PN.	USPAT
50	BRS	L57	19	"5981314"	USPAT; US-PGPUB; EPO; JPO; DERWENT
51	BRS	L58	15	5981314.URPN.	USPAT
52	BRS	L59	30	( "4508758"   "4530152"   "4890383"   "5102829"   "5126818"   "5173766"   "5216278"   "5227663"   "5239198"   "5241133"   "5250470"   "5258650"   "5311060"   "5336931"   "5386342"   "5397746"   "5436203"   "5468999"   "5473512"   "5474957"   "5489059"   "5578525"   "5593926"   "5596485"   "5612513"   "5639989"   "5700981"   "5719440"   "5767447"   "5776798" ) .PN.	USPAT
53	BRS	L60	30	( "4508758"   "4530152"   "4890383"   "5102829"   "5126818"   "5173766"   "5216278"   "5227663"   "5239198"   "5241133"   "5250470"   "5258650"   "5311060"   "5336931"   "5386342"   "5397746"   "5436203"   "5468999"   "5473512"   "5474957"   "5489059"   "5578525"   "5593926"   "5596485"   "5612513"   "5639989"   "5700981"   "5719440"   "5767447"   "5776798" ) .PN.	USPAT

	Time Stamp	Comments	Error Definition	Errors
49	2002/05/17 10:15			0
50	2002/05/17 10:18			0
51	2002/05/17 10:22			0
52	2002/05/17 10:23			0
53	2002/05/17 10:23			0



	Type	L #	Hits	Search Text	DBs
1	BRS	L1	2312	257/723,724.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT
2	BRS	L2	1113	438/107,109,110,117.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT
3	BRS	L3	3364	1 2	USPAT; US-PGPUB; EPO; JPO; DERWENT
4	BRS	L4	1095	3 and (ball bump)	USPAT; US-PGPUB; EPO; JPO; DERWENT
5	BRS	L5	905	4 and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT
6	BRS	L6	803	5 and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT
7	BRS	L7	596	6 and (resin sealing encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT
8	BRS	L8	218	7 and (second near1 (chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT
9	BRS	L9	64	8 and (bga (ball adj grid adj array))	USPAT; US-PGPUB; EPO; JPO; DERWENT
10	BRS	L10	2	("5721452"   "6133637").PN.	USPAT
11	BRS	L12	34	("4954878"   "5099306"   "5109320"   "5128831"   "5222014"   "5252857"   "5291061"   "5300801"   "5323060"   "5403784"   "5422435"   "5434745"   "5466627"   "5473814"   "5477082"   "5481134"   "5494841"   "5495398"   "5496775"   "5498902"   "5498905"   "5506756"   "5508565"   "5512765"   "5512780"   "5513076"   "5535101"   "5594275"   "5639696"   "5705858"   "5715144"   "5728606"   "5729440"   "6051878").PN.	USPAT
12	BRS	L14	12	("4862322"   "5291061"   "5323060"   "5422435"   "5735030"   "5773896"   "6005778"   "6051886"   "6097097"   "6222265"   "6232148"   "6252305").PN.	USPAT
13	BRS	L16	6	("3855693"   "5148265"   "5408127"   "5814883"   "5858815"   "5950070").PN.	USPAT
14	BRS	L18	4959	(bga (ball adj grid adj array)) near2 (package packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT

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6	2002/05/17 07:44			0
7	2002/05/17 07:45			0
8	2002/05/17 07:44			0
9	2002/05/17 07:35			0
10	2002/05/17 06:55			0
11	2002/05/17 07:21			0
12	2002/05/17 07:25			0
13	2002/05/17 07:28			0
14	2002/05/17 08:09			0

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17	BRS	L23	229	22 and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT
18	BRS	L24	25	23 and (second nearl (chip semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT
19	BRS	L25	223	23 and (substrate pcb (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT
20	BRS	L26	168	25 and (resin sealing encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT
21	BRS	L27	17	("4949224"   "4996585"   "5148265"   "5200810"   "5289059"   "5347159"   "5362656"   "5365119"   "5382829"   "5387874"   "5390223"   "5416435"   "5497116"   "5528083"   "5581776"   "5663106"   "5753974").PN.	USPAT
22	BRS	L28	5	5872700.URPN.	USPAT
23	BRS	L29	215	18 and mcm	USPAT; US-PGPUB; EPO; JPO; DERWENT
24	BRS	L30	122	29 not 26	USPAT; US-PGPUB; EPO; JPO; DERWENT
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26	BRS	L33	12	("5509553"   "5525834"   "5530287"   "5578869"   "5660697"   "5660738"   "5723906"   "5724232"   "5830563"   "5837427"   "5866942"   "6080936").PN.	USPAT
27	BRS	L34	414	18 and ((multichip adj module) (multi adj chip adj module) mcm)	USPAT; US-PGPUB; EPO; JPO; DERWENT
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29	BRS	L36	199	34 not 29	USPAT; US-PGPUB; EPO; JPO; DERWENT
30	BRS	L38	124	37 not 30	USPAT; US-PGPUB; EPO; JPO; DERWENT
31	BRS	L37	124	36 not 26	USPAT; US-PGPUB; EPO; JPO; DERWENT

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18	2002/05/17 07:44			0
19	2002/05/17 07:45			0
20	2002/05/17 07:58			0
21	2002/05/17 07:54			0
22	2002/05/17 07:55			0
23	2002/05/17 08:08			0
24	2002/05/17 07:58			0
25	2002/05/17 08:01			0
26	2002/05/17 08:02			0
27	2002/05/17 08:09			0
28	2002/05/17 08:10			0
29	2002/05/17 08:10			0
30	2002/05/17 08:11			0
31	2002/05/17 08:11			0